Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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LITEON®
OPTOELECTRONICS

IR Emitter and Detector

Product Data Sheet

LTR-323DB

Spec No.: DS-50-94-0022

Effective Date: 06/10/2010

Revision: C

LITE-ON DCC

RELEASE

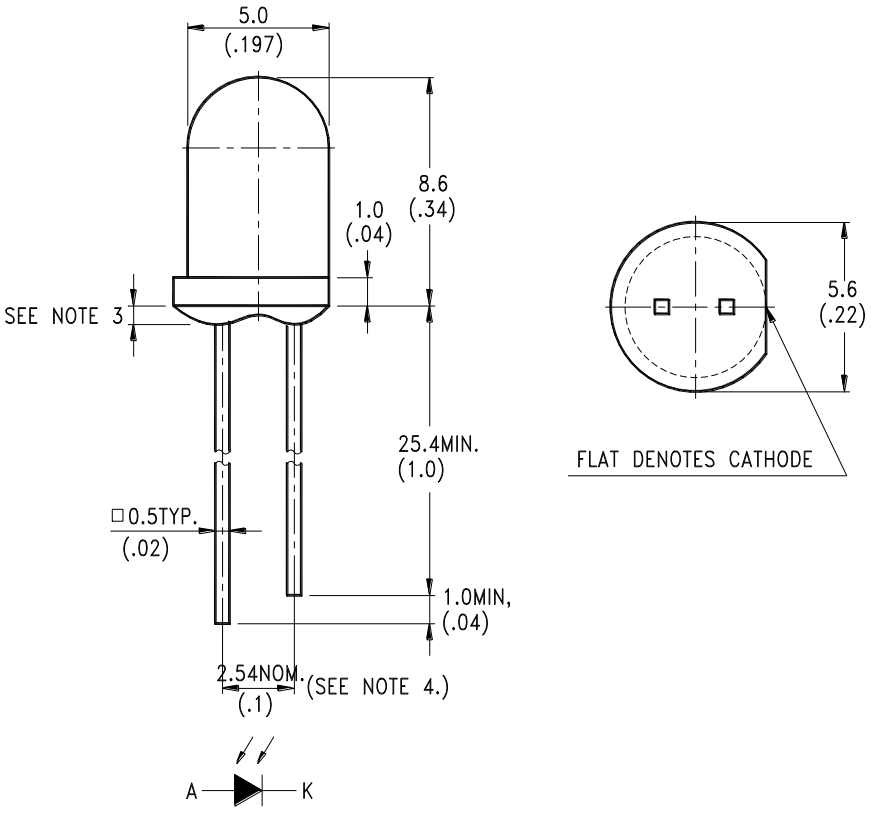
BNS-OD-FC001/A4

LITE-ON Technology Corp. / Optoelectronics
No.90,Chien 1 Road, Chung Ho, New Taipei City 23585, Taiwan, R.O.C.
Tel: 886-2-2222-6181 Fax: 886-2-2221-1948 / 886-2-2221-0660
http://www.liteon.com/opto

FEATURES

* FAST SWITCHING TIME
* THE LENS IS FOR HIGH SENSITIVITY
* LOW JUNCTION CAPACITANCE
* HIGH CUT-OFF FREQUENCY

PACKAGE DIMENSIONS



NOTES:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25mm(.010") unless otherwise noted.
3. Protruded resin under flange is 1.5mm(.059") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.

ABSOLUTE MAXIMUM RATINGS AT TA=25℃

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation	150	mW
Reverse Voltage	30	V
Operating Temperature Range	-40℃ to + 85℃	
Storage Temperature Range	-55℃ to + 100℃	
Lead Soldering Temperature [1.6mm(.063") From Body]	260℃ for 5 Seconds	

ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25℃

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Reverse Break Down Voltage	$V_{(BR)R}$	30			V	I_R = 100 μA Ee = 0mW/cm²
Reverse Dark Current Voltage	$I_{D(R)}$			30	nA	V_R = 10V Ee = 0mW/cm²
Open Circuit Voltage	V_{OC}		350		mV	λ = 940nm Ee = 0.5mW/cm²
Rise Time	Tr		50		nsec	V_R = 10V λ = 940nm R_L = 1KΩ
Fall Time	Tf		50		nsec	
Short Circuit Current	Is	8	13		μA	V_R = 5V λ = 940nm Ee = 0.1mW/cm²
Total Capacitance	C_T		25		P	V_R = 3V f = 1MHZ Ee = 0mW/cm²
Wavelength of the Max Sensitivity	λ_{SMAX}		900		nm	

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25℃ Ambient Temperature Unless Otherwise Noted)

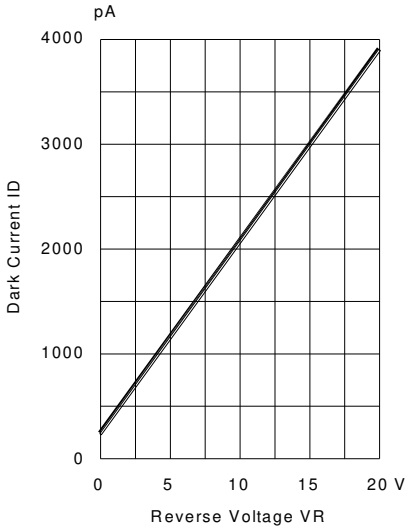


Fig.1 DARK CURRENT VS. REVERSE VOLTAGE
TA=25° C, Ee=0 mW/cm²

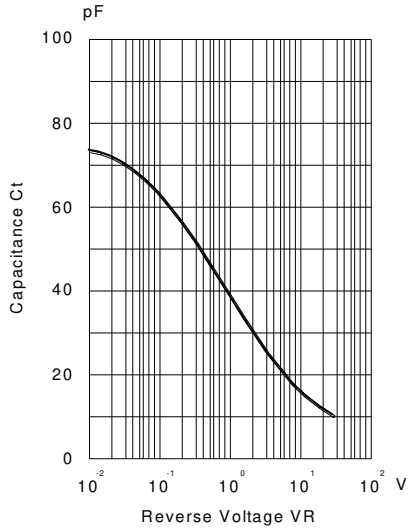


Fig.2 CAPACITANCE VS. REVERSE VOLTAGE
F=1MHZ; Ee=0mW/cm²

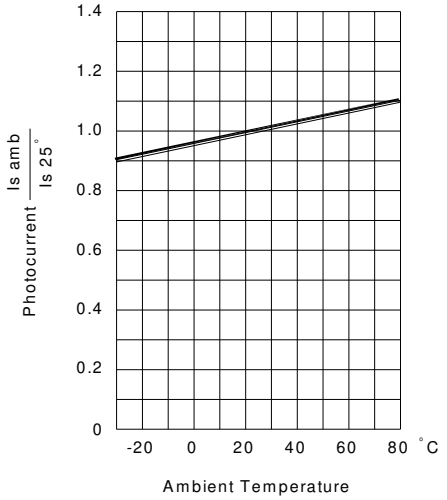


Fig.3 PHOTOCURRENT VS. AMBIENT TEMPERATURE

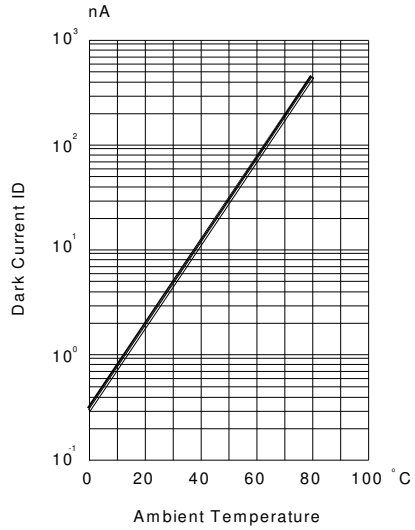


Fig.4 DARK CURRENT AMBIENT TEMPERATURE
VR=10, Ee=0mW/cm²

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25℃ Ambient Temperature Unless Otherwise Noted)

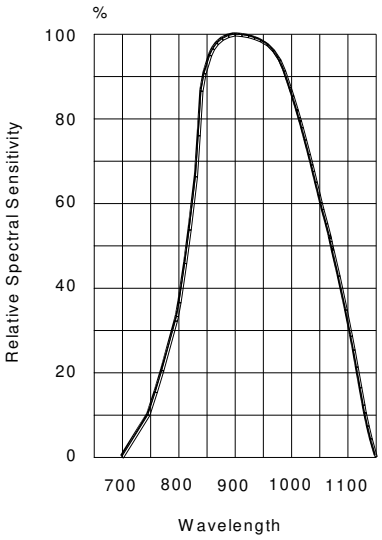


Fig.5 RELATIVE SPECTRAL SENSITIVITY VS WAVELENGTH

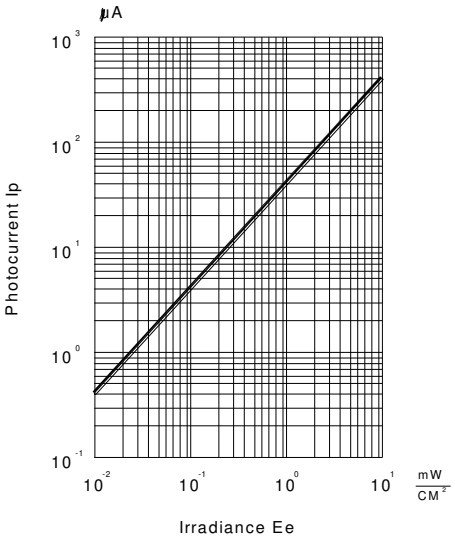


Fig.6 PHOTOCURRENT VS IRRADIANCE λ= 940 nm

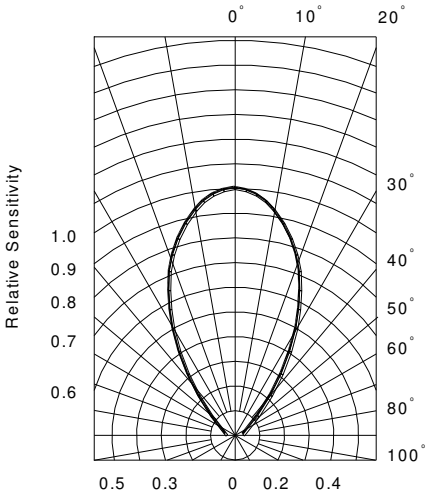


Fig.7 SENSITIVITY DIAGRAM

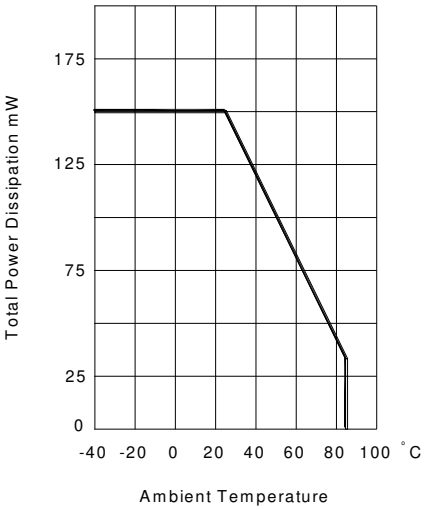


Fig.8 TOTAL POWER DISSIPATION VS AMBIENT TEMPERATURE